TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62501P,TD62501F,TD62502P,TD62502F,TD62503P,TD62503F,TD62504P TD62504F,TD62505P,TD62505F,TD62506P,TD62506F,TD62507P,TD62507F

### 7CH SINGLE DRIVER

TD62501, 502, 503, 504P / F : COMMON EMITTER

TD62505, 506P / F : COMMON COLLECTOR

TD62507P / F : ISOLATED

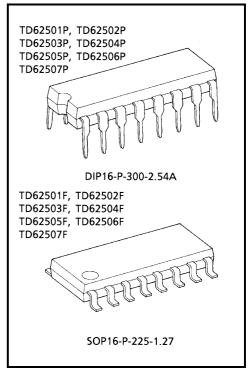
The TD62501P / F Series are comprised of seven or five NPN Transistor Arrays.

For proper operation, the substrate (SUB) must be connected to the most negative voltage.

Applications include relay, hammer, Lamp and display (LED) drivers.

### **FEATURES**

- Output Current (Single Output) 200 mA MAX.
- High Sustaining Voltage Output 35 V MIN.
- Inputs Compatible with Various Types of Logic.
- TD62501P / F, TD62505P / F and TD62507P / F: Using external resistor...General Purpose
- TD62502P / F
  - : RIN =  $10.5 \text{ k}\Omega + 7\text{V}$  Zener Diode... $14 \sim 25 \text{ V}$  P-MOS
- TD62503P / F, TD62506P / F
  - : RIN = 2.7 k $\Omega$ ···TTL, 5 V C-MOS
- TD62504P / F, : RIN =  $10.5 \text{ k}\Omega \cdot \cdot \cdot 6 \sim 15 \text{ V P-MOS}$ , C-MOS
- Package Type-P: DIP-16 pin
- Package Type-F: SOP-16 pin

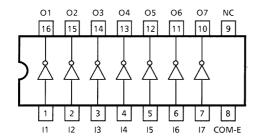


Weight

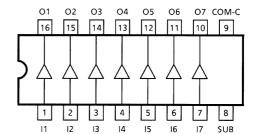
DIP16-P-300-2.54A : 1.11 g (Typ.) SOP16-P-225-1.27 : 0.16 g (Typ.)

# PIN CONNECTION (Top view)

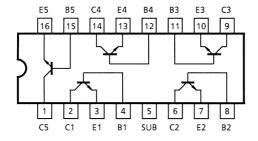
TD62501P / F, TD62502P / F TD62503P / F, TD62504P / F



TD62505P / F, TD62506P / F

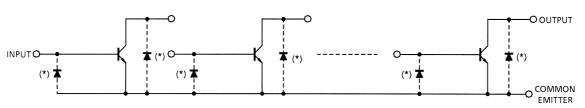


TD62507P / F

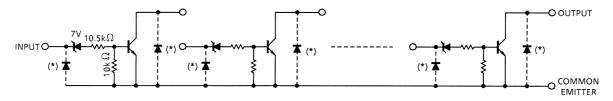


# **SCHEMATICS** (Each driver)

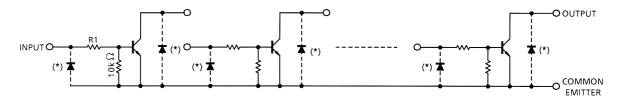
TD62501P / F



TD62502P / F



TD62503P / F TD62504P / F



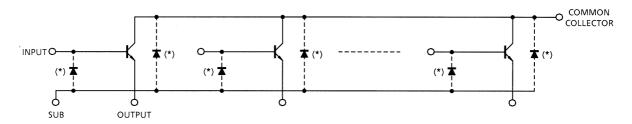
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TD62503P / F R1 = 2.7 kΩ, TD62504P / F R1 = 10.5 kΩ

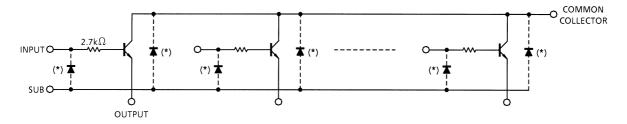
### \*: Parasitic Diodes

# **SCHEMATICS** (Each driver)

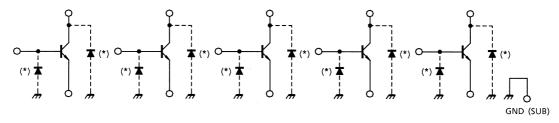
### TD62505P / F



### TD62506P / F



### TD62507P / F



\*: Parasitic Diodes

Note: The input and output parasitic diodes cannot be used as clamp diodes.

# MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

CHARACTERIST	SYMBOL	RATING	UNIT		
Collector-Emitter Voltage	$V_{CEO}$	35	V		
Collector-Base Voltage	V <sub>CBO</sub>	50	V		
Collector Current	Ic	200	mA / ch		
Input Voltage	V <sub>IN</sub> (Note 1)	-0.5~45	V		
Input Voltage	V <sub>IN</sub> (Note 2)	-0.5~30	V		
Input Current	I <sub>IN</sub> (Note 3)	25	mA		
Isolation Voltage		V <sub>SUB</sub>	35	V	
Power Dissination	Р	Dr.	1.0	W	
Power Dissipation	F	PD	0.625 (Note 4)		
Operating Temperature		T <sub>opr</sub>	-40~85	°C	
Storage Temperature		T <sub>stg</sub>	-55~150	°C	

Note 1: TD62506P / F

Note 2: TD62502P / F, TD62503P / F, TD62504P / F Note 3: TD62501P / F, TD62505P / F, TD62507P / F Note 4: On Glass Epoxy PCB ( $30 \times 30 \times 1.6$  mm, Cu 50%)



# RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)

CHARAC	TERISTIC	SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT
Collector-Emitter \	/oltage	V <sub>CEO</sub>		0	_	35	V
Collector-Base Vo	ltage	V <sub>CBO</sub>		0	_	50	V
Collector Current		Ic		0	_	150	mA / ch
Input Voltage	TD62506P / F	V <sub>IN</sub>		0	_	35	V
	TD62502P / F					25	
	TD62503P / F			0	_		
	TD62504P / F						
Input Current	TD62501P / F	I <sub>IN</sub>		0	_	10	mA
	TD62505P / F						
	TD62507P / F						
Power Dissipation	Р	P <sub>D</sub>		_	_	0.360	W
	F		On PCB (Note)	_	_	0.325	

Note: 30 × 30 × 1.6 mm, Cu 50%

# **ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)**

CHARACTERISTIC		SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Output Leakage Current		I <sub>CEX</sub>	1	V <sub>CE</sub> = 25 V, V <sub>IN</sub> = 0	_	_	10	μA
Collector-Emitter Saturation Voltage		V <sub>CE</sub> (sat)		I <sub>IN</sub> = 1 mA, I <sub>C</sub> = 10 mA	_	_	0.2	٧
			2	I <sub>IN</sub> = 3 mA, I <sub>C</sub> = 150 mA		_	0.8	
				(Note 1)	-			
DCCurrent Transfer Ratio	(Note 2)	h <sub>FE</sub>	2	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 10 mA	70	_	_	
	(Note 3)				50	_	_	
Input Voltage	TD62502P / F	V <sub>IN</sub> (ON)	3	I <sub>IN</sub> = 1 mA I <sub>C</sub> = 10 mA	13	17	23	
	TD62503P / F				2.4	3.4	4.2	V
	TD62504P / F				7.5	11.5	15	
Turn-On Delay		t <sub>ON</sub>	4	V <sub>OUT</sub> = 35 V, R <sub>L</sub> = 3.3 kΩ C <sub>L</sub> = 15 pF	_	50	_	- ns
Turn-Off Delay		t <sub>OFF</sub>			_	200	_	

Note 1: Except TD62502P / F Only

Note 2: Only TD62501P / F, TD62505P / F, TD62506P / F, TD62507P / F

Note 3: Only TD62502P / F, TD62503P / F, TD62504P / F

### **TEST CIRCUIT**

### 1. ICEX

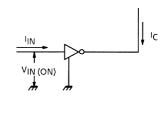
# OPEN CEX VCE

# 2. hFE, VCE (sat)

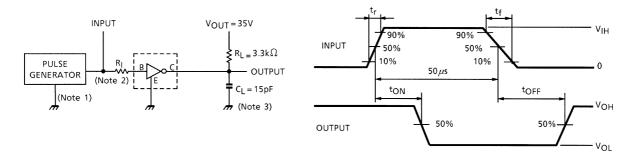
$$\frac{I_{\text{IN}}}{V_{\text{CE}}, V_{\text{CE}} \text{ (sat)}}$$

$$h_{\text{FE}} = \frac{I_{\text{C}}}{I_{\text{IN}}}$$

# 3. VIN (ON)



### 4. ton, toff



Note 1: Pulse Width 50 µs, Duty Cycle 10%

Output Impedance 50  $\Omega$ ,  $t_f \le 5$  ns,  $t_f \le 10$  ns

Note 2: See below

## **INPUT CONDITION**

TYPE NUMBER	RĮ	VIH
TD62501P / F	2.7 kΩ	3 V
TD62502P / F	0 Ω	15 V
TD62503P / F	0 Ω	3 V
TD62504P / F	0 Ω	10 V
TD62505P / F	2.7 kΩ	3 V
TD62506P / F	0 Ω	3 V
TD62507P / F	2.7 kΩ	3 V

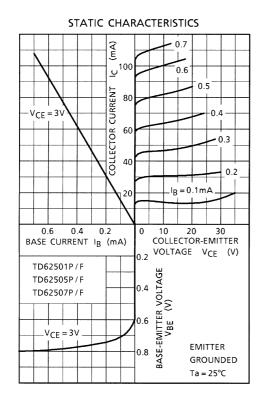
Note 3: C<sub>L</sub> includes probe and jig capacitance

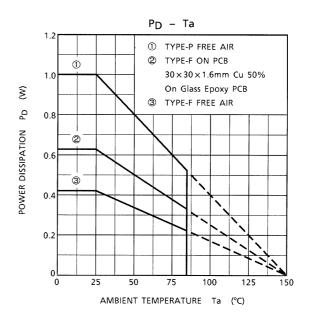
### **PRECAUTIONS for USING**

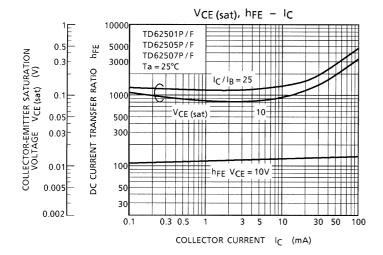
This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

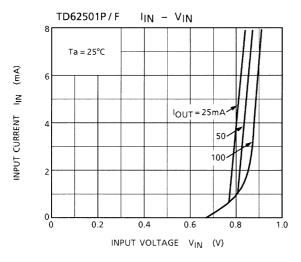
Utmost care is necessary in the design of the output line,  $V_{CC}$  and GND line since IC may be destroyed due to short–circuit between outputs, air contamination fault, or fault by improper grounding.

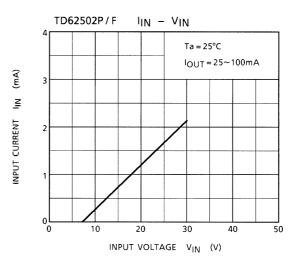


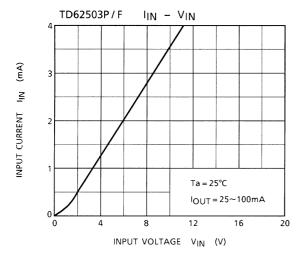


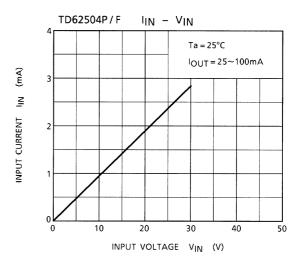


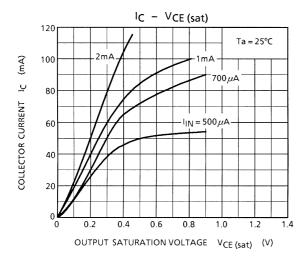
6 2001-07-04





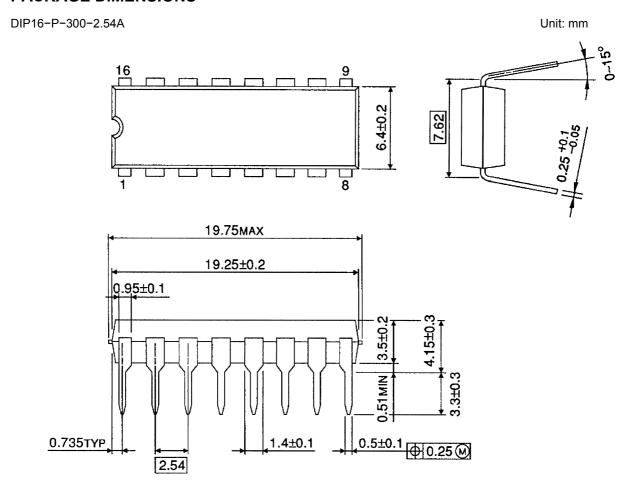






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# **PACKAGE DIMENSIONS**

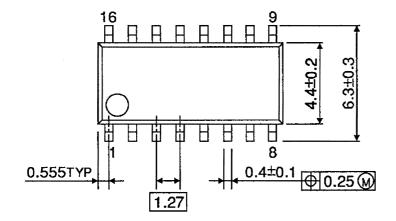


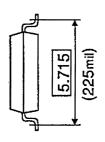
Weight: 1.11 g (Typ.)

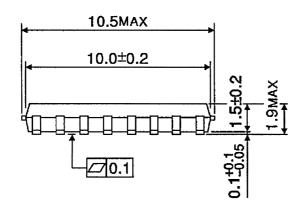
# **PACKAGE DIMENSIONS**

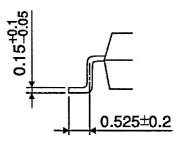
SOP16-P-225-1.27

Unit: mm









Weight: 0.16 g (Typ.)

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# RESTRICTIONS ON PRODUCT USE

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